

Title (en)

FPCB, SMART CARD AND PACKAGING METHOD THEREFOR

Title (de)

FPCB, CHIPKARTE UND VERKAPSELUNGSVERFAHREN DAFÜR

Title (fr)

FPCB, CARTE À PUCE INTELLIGENTE ET LEUR PROCÉDÉ D'ENCAPSULATION

Publication

EP 3761765 A4 20210428 (EN)

Application

EP 19767641 A 20190124

Priority

- CN 201810199686 A 20180312
- CN 2019072994 W 20190124

Abstract (en)

[origin: EP3761765A1] Disclosed are an FPCB, a smart card, and a packaging method thereof. A first component (5) and a second component (6) are disposed on the FPCB (4), and a through groove (41) is disposed on the FPCB (4) in a position of the second component (6), where the through groove (41) is configured to enable the FPCB (4) to provide a deformation space when the second component (6) and the first component (5) are positioned on an upper substrate (1). The deformation is used to adjust a processing error between the two components, so as to position and fasten the two components on the FPCB (4), thereby avoiding a defective appearance or function caused by displacement of the two positions of the two components that is resulted from the production processing error, and further ensuring that components on the smart card (100) meet appearance and function requirements and increasing a production yield rate of the smart card (100).

IPC 8 full level

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CPC (source: CN EP)

H05K 1/18 (2013.01 - CN); **H05K 1/189** (2013.01 - EP); **H05K 3/303** (2013.01 - EP); **H05K 3/326** (2013.01 - EP); **G06K 19/07745** (2013.01 - EP); **H05K 1/028** (2013.01 - EP); **H05K 1/183** (2013.01 - EP); **H05K 3/4697** (2013.01 - EP); **H05K 2201/09036** (2013.01 - CN EP); **H05K 2201/09063** (2013.01 - EP); **H05K 2201/091** (2013.01 - EP); **H05K 2201/10128** (2013.01 - EP); **H05K 2201/10431** (2013.01 - EP); **Y02P 70/50** (2015.11 - EP)

Citation (search report)

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- [I] KR 101760675 B1 20170724 - MANEUL LAB INC [KR]
- [A] EP 2398654 A1 20111228 - HID GLOBAL GMBH [DE]
- [A] US 2015373827 A1 20151224 - GUO JUNSHENG [CN], et al
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Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

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